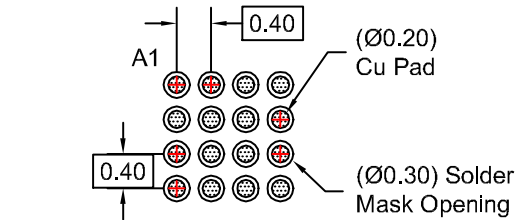
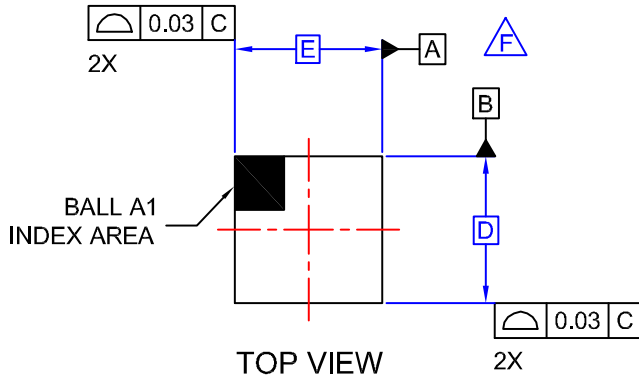


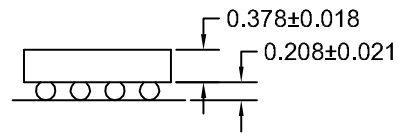
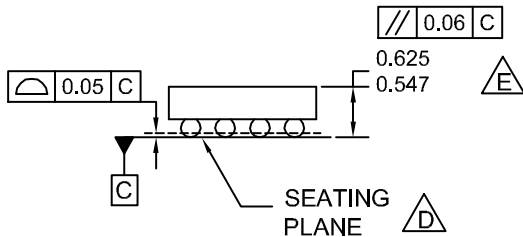


WLCSP16 1.71x1.71x0.586
CASE 567SC
ISSUE O

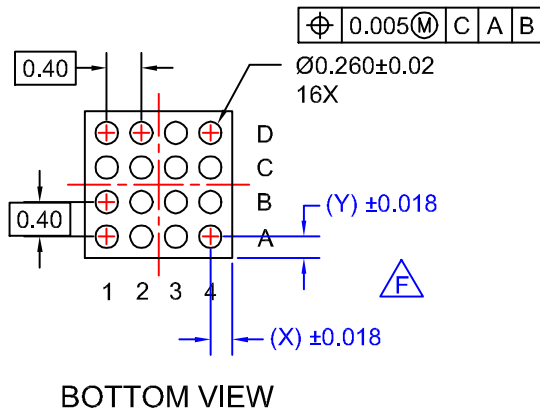
DATE 30 NOV 2016



**RECOMMENDED LAND PATTERN
(NSMD PAD TYPE)**



SIDE VIEWS



BOTTOM VIEW

NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 1994.
- D** DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E** PACKAGE NOMINAL HEIGHT IS 586 MICRONS ±39 MICRONS (547-625 MICRONS).
- F** FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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DESCRIPTION:	WLCSP16 1.71x1.71x0.586	PAGE 1 OF 1

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